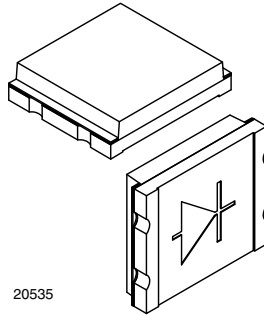


Silicon PIN Photodiode



DESCRIPTION

TEMD5010X01 is a high speed and high sensitive PIN photodiode. It is a miniature surface mount device (SMD) including the chip with a 7.5 mm² sensitive area detecting visible and near infrared radiation.

FEATURES

- Package type: surface mount
- Package form: top view
- Dimensions (L x W x H in mm): 5 x 4.24 x 1.12
- Radiant sensitive area (in mm²): 7.5
- AEC-Q101 qualified
- High photo sensitivity
- High radiant sensitivity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\phi = \pm 65^\circ$
- Floor life: 72 h, MSL 4, acc. J-STD-020
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



Note

** Please see document "Vishay Material Category Policy": www.vishay.com/doc?99902

APPLICATIONS

- High speed photo detector

| PRODUCT SUMMARY | | | |
|-----------------|----------------------|---------|-------------|
| COMPONENT | I _{ra} (μA) | φ (deg) | λ0.1 (nm) |
| TEMD5010X01 | 55 | ± 65 | 430 to 1100 |

Note

- Test conditions see table "Basic Characteristics"

| ORDERING INFORMATION | | | |
|----------------------|---------------|------------------------------|--------------|
| ORDERING CODE | PACKAGING | REMARKS | PACKAGE FORM |
| TEMD5010X01 | Tape and reel | MOQ: 1500 pcs, 1500 pcs/reel | Top view |

Note

- MOQ: minimum order quantity

| ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified) | | | | |
|---|-----------------------------------|-------------------|---------------|------|
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| Reverse voltage | | V _R | 60 | V |
| Power dissipation | T _{amb} ≤ 25 °C | P _V | 215 | mW |
| Junction temperature | | T _j | 100 | °C |
| Operating temperature range | | T _{amb} | - 40 to + 100 | °C |
| Storage temperature range | | T _{stg} | - 40 to + 110 | °C |
| Soldering temperature | Acc. reflow solder profile fig. 8 | T _{sd} | 260 | °C |
| Thermal resistance junction/ambient | | R _{thJA} | 350 | K/W |



| BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) | | | | | | |
|---|---|-----------------|------|---------------------|------|-----------------------------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Forward voltage | $I_F = 50\text{ mA}$ | V_F | | 1 | 1.3 | V |
| Breakdown voltage | $I_R = 100\text{ }\mu\text{A}$, $E = 0$ | $V_{(BR)}$ | 60 | | | V |
| Reverse dark current | $V_R = 10\text{ V}$, $E = 0$ | I_{ro} | | 2 | 30 | nA |
| Diode capacitance | $V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$ | C_D | | 70 | | pF |
| | $V_R = 3\text{ V}$, $f = 1\text{ MHz}$, $E = 0$ | C_D | | 25 | 40 | pF |
| Open circuit voltage | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | V_o | | 350 | | mV |
| Temperature coefficient of V_o | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | TK_{V_o} | | -2.6 | | mV/K |
| Short circuit current | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | I_k | | 50 | | μA |
| Temperature coefficient of I_k | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | TK_{I_k} | | 0.1 | | %/K |
| Reverse light current | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$, $V_R = 5\text{ V}$ | I_{ra} | 45 | 55 | | μA |
| Angle of half sensitivity | | ϕ | | ± 65 | | deg |
| Wavelength of peak sensitivity | | λ_p | | 940 | | nm |
| Range of spectral bandwidth | | $\lambda_{0.1}$ | | 430 to 1100 | | nm |
| Noise equivalent power | $V_R = 10\text{ V}$, $\lambda = 950\text{ nm}$ | NEP | | 4×10^{-14} | | $\text{W}/\sqrt{\text{Hz}}$ |
| Rise time | $V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 820\text{ nm}$ | t_r | | 100 | | ns |
| Fall time | $V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 820\text{ nm}$ | t_f | | 100 | | ns |

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

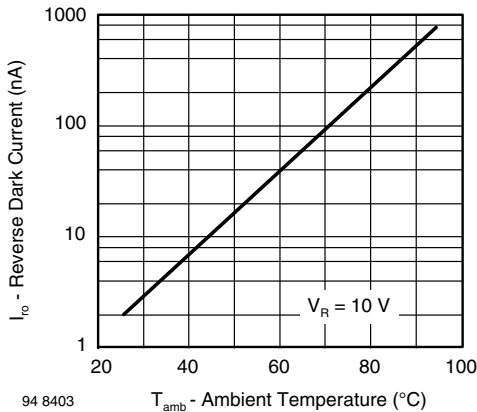


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

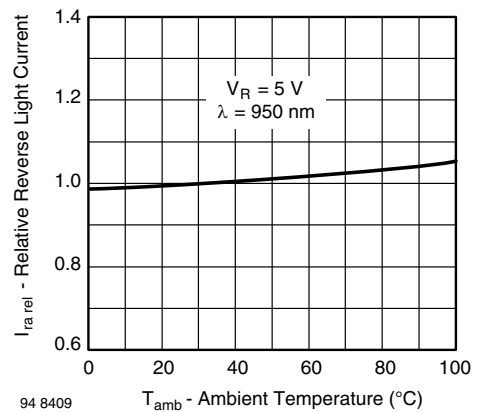
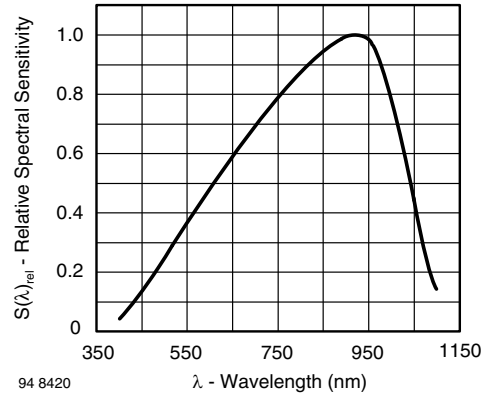


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature



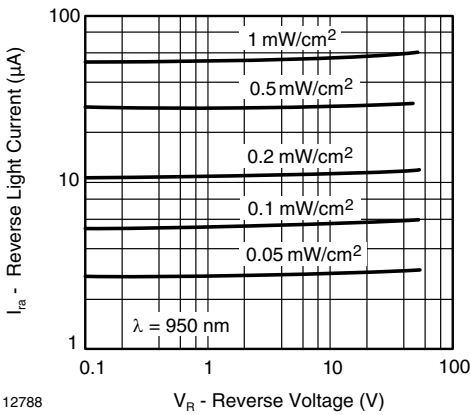
12787

Fig. 3 - Reverse Light Current vs. Irradiance



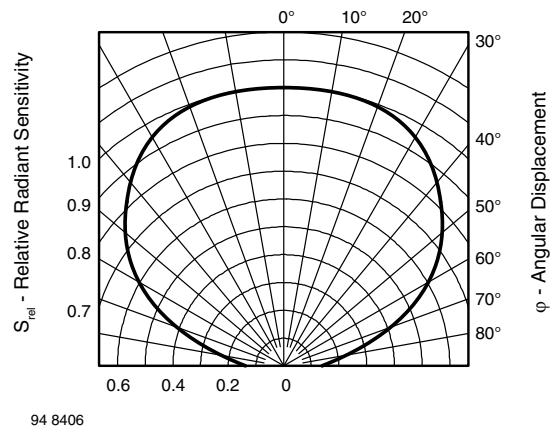
94 8420

Fig. 6 - Relative Spectral Sensitivity vs. Wavelength



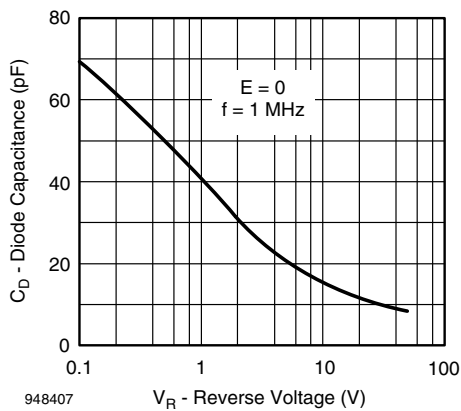
12788

Fig. 4 - Reverse Light Current vs. Reverse Voltage



94 8406

Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

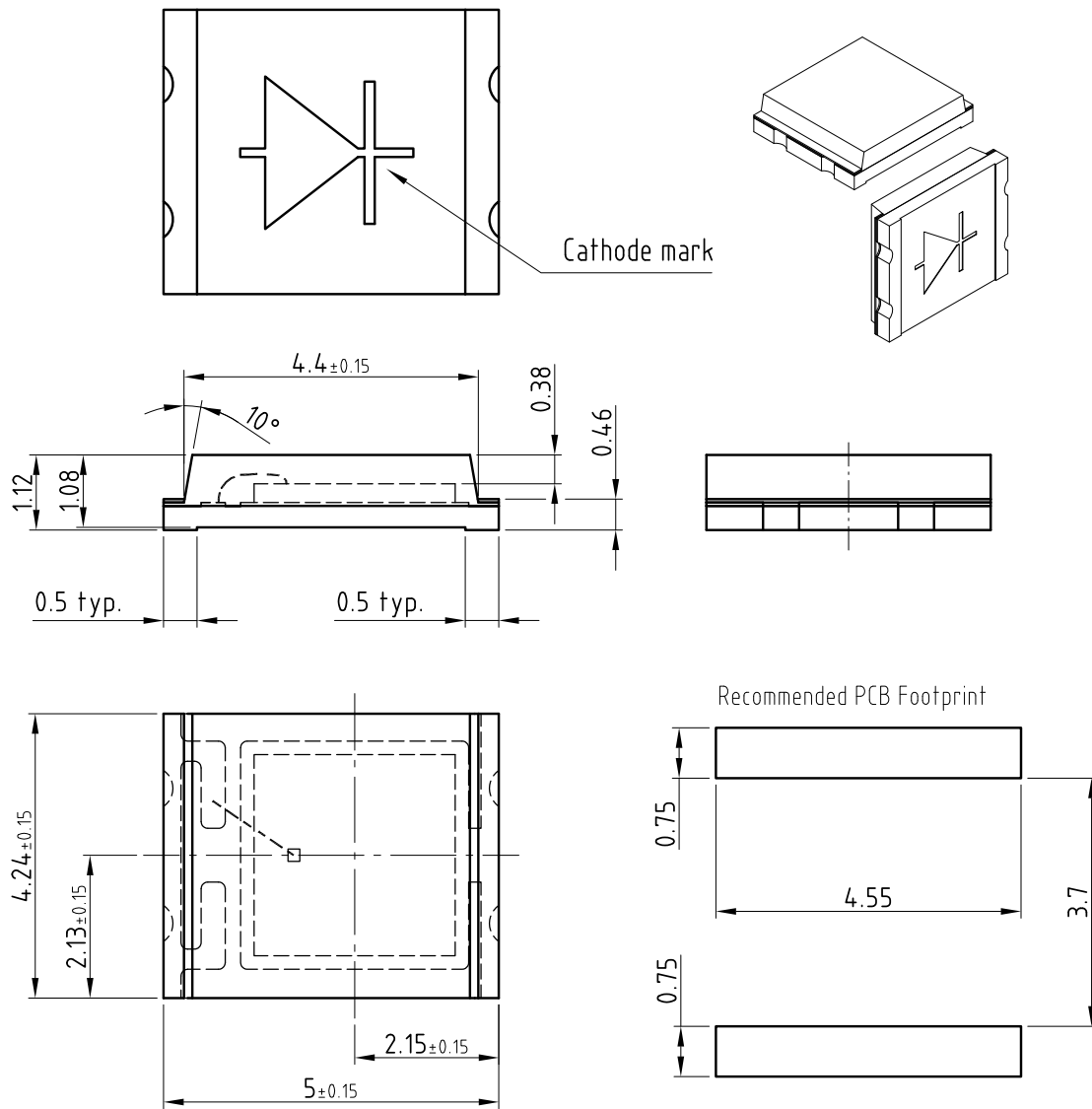


948407

Fig. 5 - Diode Capacitance vs. Reverse Voltage



PACKAGE DIMENSIONS in millimeters



Cathode mark

Recommended PCB Footprint



Technical drawings according to DIN specifications

Drawing-No.: 6.541-5060.01-4
Issue: 3; 05.02.08
20536

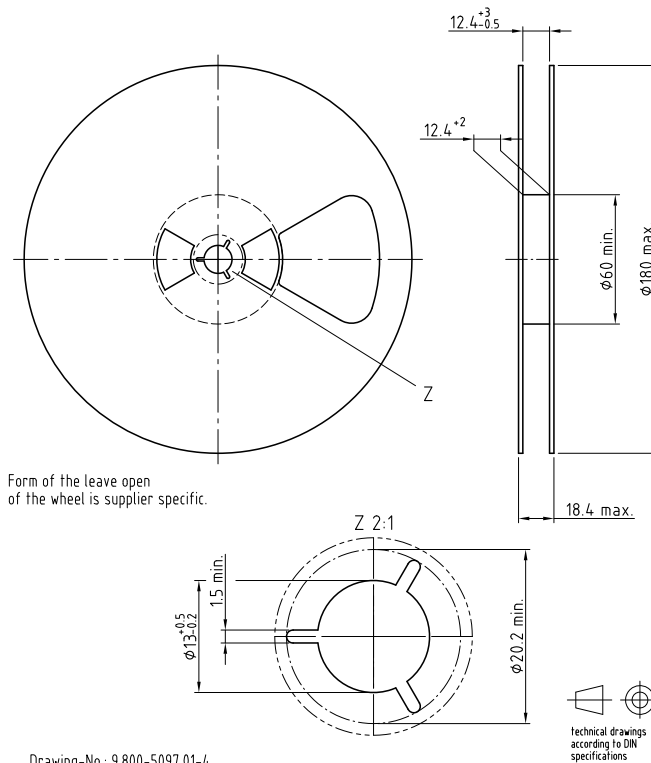
Not indicated tolerances ± 0.1

TAPING DIMENSIONS in millimeters



Drawing-No.: 9.700-5293.01-4
 Issue: 1; 03.12.04
 20537

REEL DIMENSIONS in millimeters



Drawing-No.: 9.800-5097.01-4
 Issue: 1; 05.05.08
 20874

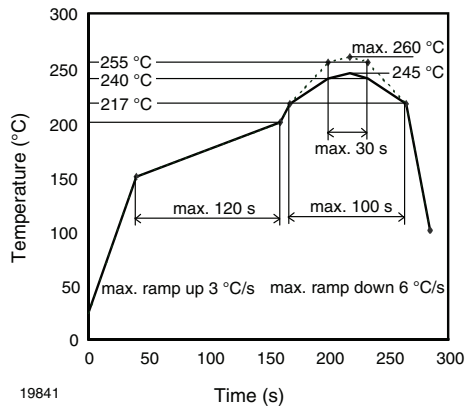
SOLDER PROFILE


Fig. 8 - Lead (Pb)-free Reflow Solder Profile
acc. J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 4

Floor life: 72 h

Conditions: $T_{amb} < 30\text{ °C}$, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %.



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